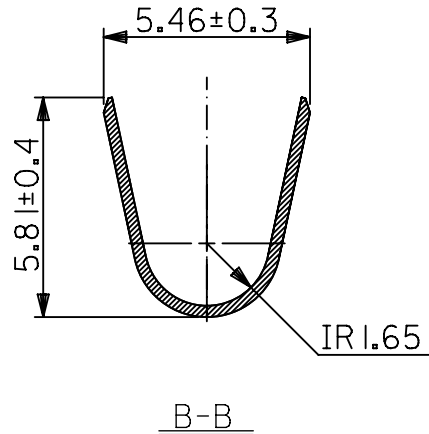
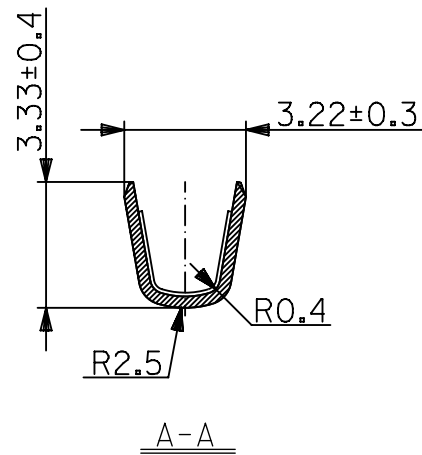
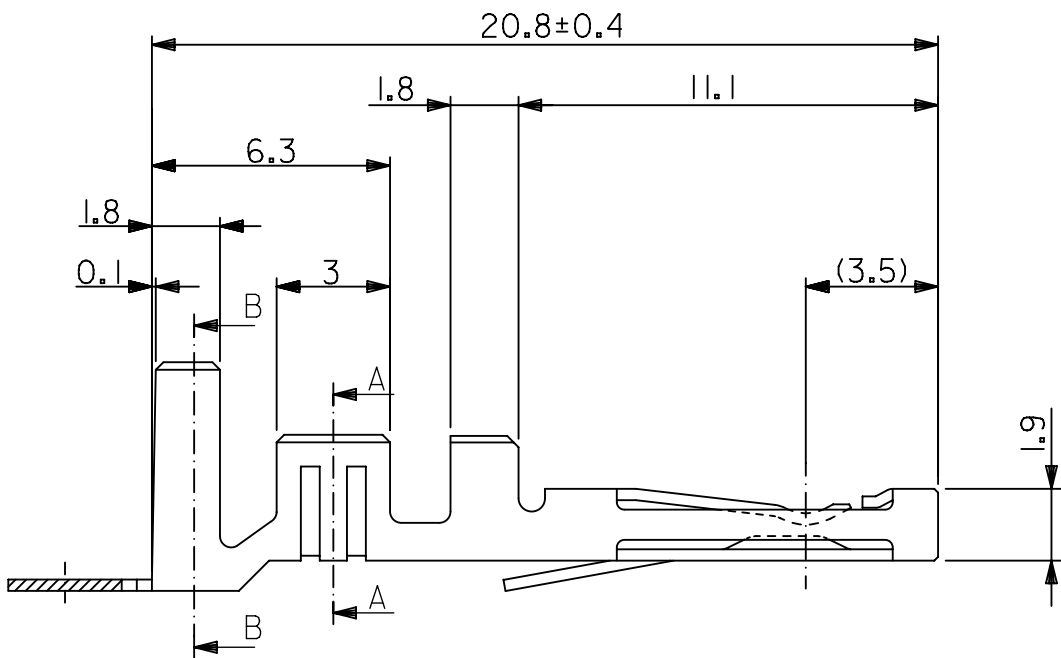
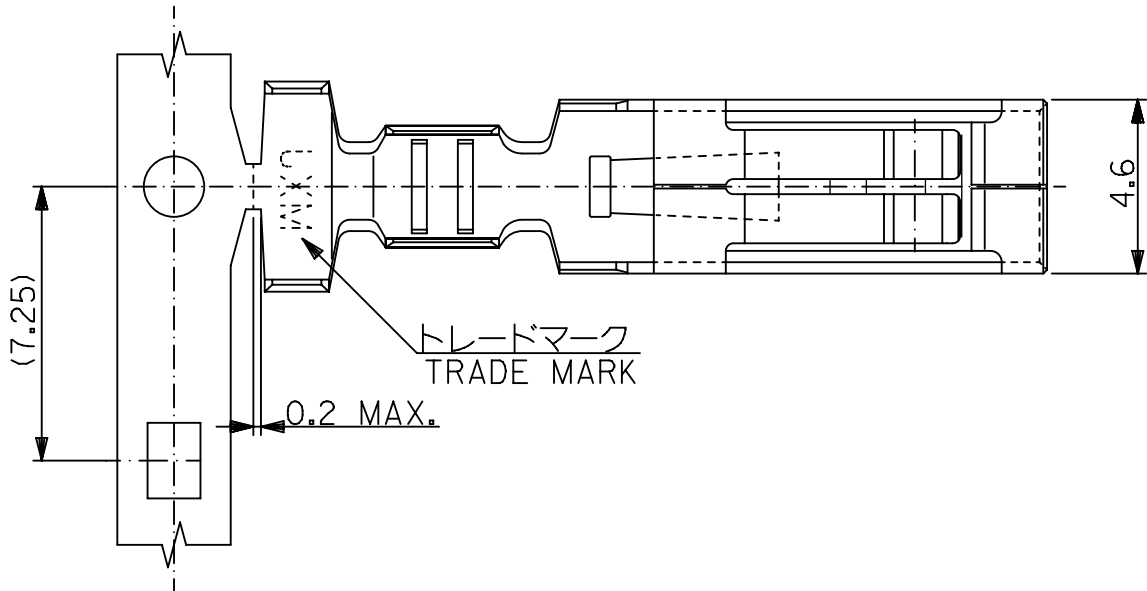
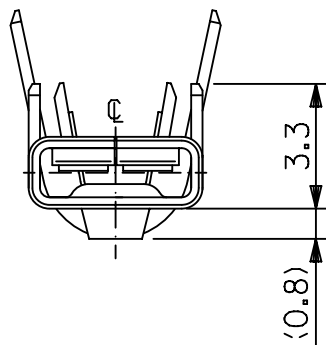




注記)
NOTES:

- 材質
MATERIAL
銅合金 (板厚: 0.3)
COPPER ALLOY (THICKNESS: 0.3)
- メッキ仕様
TERMINAL PLATING
接点部: 金メッキ 0.1µm MIN.
CONTACT AREA: GOLD 0.1 MICROMETER MINIMUM.
パラジウムニッケルメッキ 0.6µm MIN.
PALLADIUM NICKEL 0.6 MICROMETER MINIMUM.
圧着部: 錫メッキ 1.0µm MIN.
CRIMP AREA: TIN 1.0 MICROMETER MINIMUM.
下地メッキ: ニッケルメッキ 1.5µm MIN.
UNDER PLATE: NICKEL 1.5 MICROMETER MINIMUM.
- 適用電線範囲:
APPLICABLE WIRE RANGE:
UL 1015 AWG*#18~14
UL 1865 AWG*#16~14
- 被覆外径: ø 3.8 MAX.
INSULATION EXTERNAL DIA: ø3.8 MAX.
- 適用ハウジングアッセンブリ: 53777シリーズ
APPLICABLE HOUSING ASS'Y: 53777 SERIES
- 適用ハウジング: 54084-0305
APPLICABLE HOUSING: 54084-0305
- 本製品は50637-**-49の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 50637-**-49.



	バラ状 LOOSE	50637-0128
50637-**-28	連鎖状 CHAIN	50637-0028
MODEL No.	端子形状 TERMINAL CONFIGURATION	MATERIAL No.

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION											
DIMENSION UNITS		SCALE		CURRENT REV DESC: RETRACTED AS PER THE REQUEST CASE #01114726				molex			
mm		5:1									
GENERAL TOLERANCES (UNLESS SPECIFIED) ANGULAR TOL ± ° 4 PLACES ± 3 PLACES ± 2 PLACES ± 1 PLACE ± 0 PLACES ± DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				EC NO: 831459				AC/DC CONN. REC. CRIMP TERM. -LEAD FREE-			
				DRWN: VISHAH2							
				CHK'D: GB							
				APPR: GB				PRODUCT CUSTOMER DRAWING			
				INITIAL REVISION:				DOCUMENT NUMBER		DOC TYPE	
DRWN: HKAWABATA				SD-50637-001		PSD		001		B	
APPR: MSASAO				2004/05/27							
THIRD ANGLE PROJECTION		DRAWING		SERIES		MATERIAL NUMBER		CUSTOMER		SHEET NUMBER	
		B-SIZE		50637		SEE TABLE		GENERAL MARKET		1 OF 1	

DOCUMENT STATUS	P1	RELEASE DATE	2025/08/13	13:39:27
-----------------	----	--------------	------------	----------